

L Number	Hits	Search Text	DB	Time stamp
1	0	174.68.1.ccls. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 00:51
2	21	174/68.1.ccls. and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 01:07
3	4469	((flex\$4 or bend\$4) near (chip or die)) and (cable or board or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 02:16
4	1318	((flex\$4 or bend\$4) near (chip or die)) and (cable or board or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 01:11
5	1192	((flex\$4 or bend\$4) near (chip or die)) and (cable or board or substrate)) and (@ad<20010604)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 02:14
6	1	("4810917").PN.	USPAT	2002/12/15 02:14
7	8	4810917.URPN.	USPAT	2002/12/15 02:14
8	1	((flex\$4 or bend\$4) near (chip or die)) and ((round or ball or curve) near (substrte or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 02:18
9	31	((flex\$4 or bend\$4) near (chip or die)) and ((round or ball or curve) near (substrate or board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 02:21
10	466	((flex\$4 or bend\$4) near (chip or die)) and holder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/15 02:23